





Substrate: 0.635mm ±0.18mm [0.025" ±0.007"] per IPC 4101/21, Gold surface finish.



Substrate: 1.59mm ±0.18mm [0.062" ±0.007"] FR4/G10 or equivalent high temp material. Non-clad.



Pins: shell material- Brass Alloy 360 1/2 hard; finish- $0.25\mu m$ [10 μ "] Au over $1.27\mu m$ [50 μ "] Ni (min.). Contact material- BeCu; finish $0.25\mu m$ [10 μ "] Au over $2.54\mu m$ [100 μ "] Ni (min.).

RoHS COMPLIANT

<u>Description:</u> 20 position MLF surface mount foot 20 position (+1 Gnd index pin). 1.0mm pitch UGA female receptacles (top) to 20 position, 0.8mm MLF pattern

SF-QFN20E-L-02 Drawing	Status: Released	Scale	8:1	Rev: A
© 2005 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 11/21/05	
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